Advanced Packaging Tutorials 先進封裝教程：

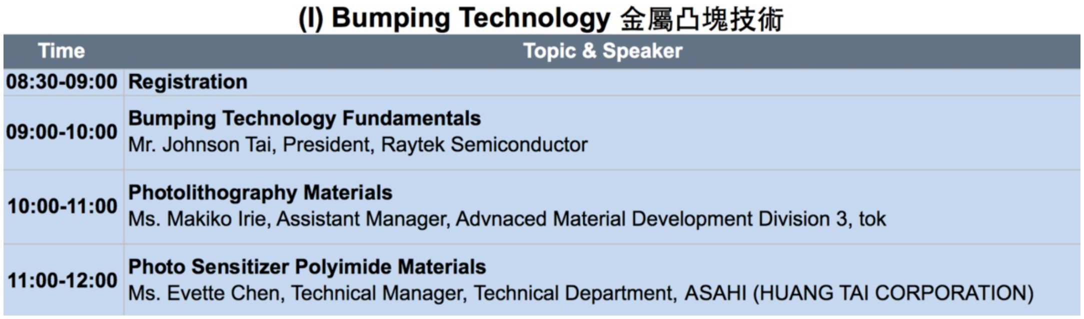
先進封裝技術人才近年來成為職場最缺乏的專業人才之一，其原因源於晶圓製程技術超微縮的結果，傳統封裝形式已經無法解決元件高性能，超薄短小又省電的需求，使得後段封測廠需求人才甚多甚急，SEMI Taiwan有鑑於有志從事半導體先進封裝技術的初學者及學生未來想進入先進封裝行業，特別於半導體展期間推出一系列三天先進封裝技術的基本教程，參加的學員可以經由此經心設計的課程一探究竟，以作為未來進入職場做準備。

三個半天的課程首先介紹金屬凸塊技術(Bump Technology)及有機絕緣材料的應用，第二天進入先進封裝技術，晶片研磨(Grinding)、切割(Dicing)及晶片貼合技術(Chip Attach)，第三天介紹壓模(Molding)及封裝故障分析等，學員經過這三個半天的教程即可一覽先進封裝基本知識，課程講師均由業界具有生產實務的技術專家擔任。

時間: September 13 ~ 15
地點: 台北市11568南港區經貿二路1號 (南港展覽館一館6F 614會議室)
See Map

Agenda

Day 1, September 13, Wednesday

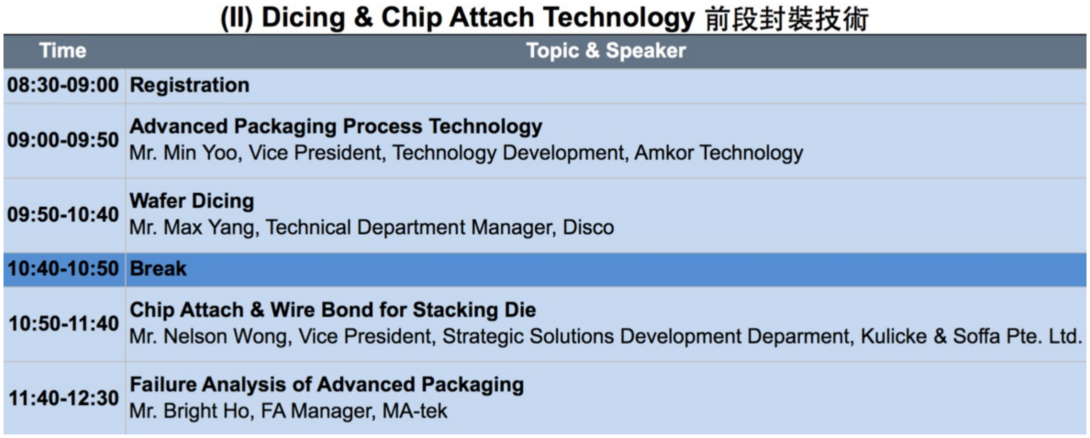


(I) Bumping Technology 金屬凸塊技術

Time	Topic & Speaker
08:30-09:00	**Registration**
09:00-10:00	**Bumping Technology Fundamentals** Mr. Johnson Tai, President, Raytek Semiconductor
10:00-11:00	**Photolithography Materials** Ms. Makiko Irie, Assistant Manager, Advnaced Material Development Division 3, tok
11:00-12:00	**Photo Sensitizer Polyimide Materials** Ms. Evette Chen, Technical Manager, Technical Department, ASAHI (HUANG TAI CORPORATION)

Registration - Day 1

Day 2, September 14, Thursday



(II) Dicing & Chip Attach Technology 前段封裝技術

Time	Topic & Speaker
08:30-09:00	**Registration**
09:00-09:50	**Advanced Packaging Process Technology** Mr. Min Yoo, Vice President, Technology Development, Amkor Technology
09:50-10:40	**Wafer Dicing** Mr. Max Yang, Technical Department Manager, Disco
10:40-10:50	**Break**
10:50-11:40	**Chip Attach & Wire Bond for Stacking Die** Mr. Nelson Wong, Vice President, Strategic Solutions Development Deparment, Kulicke & Soffa Pte. Ltd.
11:40-12:30	**Failure Analysis of Advanced Packaging** Mr. Bright Ho, FA Manager, MA-tek

Registration - Day 2

Day 3, September 15, Friday

(III) Encapsulation Technology 後段封裝技術

Time	Topic & Speaker
08:30-09:00	**Registration**
09:00-10:00	**Molding Technology for Advanced Packaging** Mr. BH Moon, Sr. Manager, Central Engineering DRAM Process Department, Micron Technology
10:00-11:00	**Substrate Technology for Advanced Packaging** Mr. Gary Chen, Sr. Vice President, Carrier SBU R&D Department, Unimicron Technology Corp.
11:00-12:00	**Assembly Metrology & Failure Analysis** Dr. Shye Shapira, Vice President, R&D Department, Camtek

Registration - Day 3

Organized by:

semi

TOP PRO
INTERNATIONAL CO., LTD.

Sponsored by:

Camtek
See Beyond

HUANG TAI CORPORATION

Kulicke & Soffa

tok

Unimicron
欣 興 電 子

Contact
TOP PRO INTERNATIONAL CO., LTD.
Mr. Matt Liang
Tel: 886-3-658-0731
Cell: 886-987-959-398
Email: mliang@topprointl.com